

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











## GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 8 GHz

### Typical Applications

The HMC168C8 is ideal for:

- Microwave Point-to-Point Radios
- 5.8 GHz ISM Band Circuits

#### **Features**

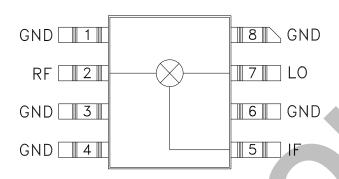
Conversion Loss: 8.2 dB

LO to RF and IF Isolation: 34 dB

Surface Mount

Small Size, No DC Bias Required

## **Functional Diagram**



### **General Description**

The HMC168C8 is a miniature double-balanced mixer in a non-hermetic ceramic surface mount package that can be used as an upconverter, downconverter or biphase modulator. The device is a passive diode/balun type mixer with high dynamic range. Noise figure is essentially equal to the conversion loss. The mixer can handle larger signal levels than most active mixers due to the high third order intercept. MMIC implementation provides exceptional balance in the circuit resulting in high LO/RF and LO/IF isolations and unit-to-unit consistency. This mixer has applications where small size and surface mount compatibility are important.

## Electrical Specifications, $T_A = +25^{\circ}$ C, LO Drive = +10 dBm

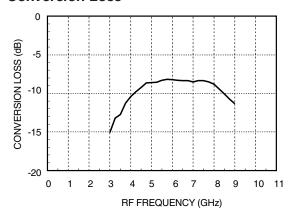
Parameter	Min.	Тур.	Max.	Units
Frequency Range, RF & LO	4.5 - 8.0			GHz
Frequency Range, IF	DC - 2			GHz
Conversion Loss		8.2	10	dB
Noise Figure (SSB)		8.2	10	dB
LO to RF Isolation	29	35		dB
LO to IF Isolation	30	34		dB
IP3 (Input)	12	16		dBm
IP2 (Input)	55	62		dBm
1 dB Gain Compression (Input)	7	10		dBm



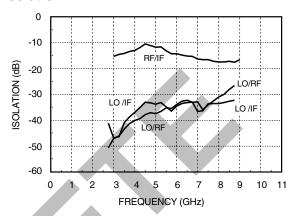


## GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 8 GHz

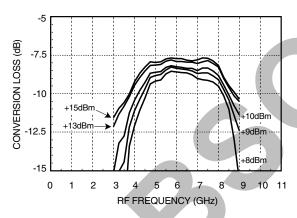
#### **Conversion Loss**



#### Isolation



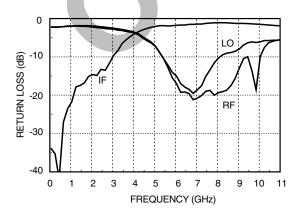
#### Conversion Loss vs. LO Power



### Distortion and 1dB Compression vs. LO Drive Level

	Disto		
LO Drive	RF (f1) = 6.01 GHz RF (f2) = 6.00 GHz LO = 6.5 GHz RF Level = 0 dBm		1 dB Compression
(dBm)	IP3 (dBm)	IP2 (dBm)	P1dB (dBm)
+7	14	59	8.5
+10	16	62	10
+13	18	65	11
+15	19	65	11

#### **Return Loss**



S - Paremeters for the RF, LO, IF Ports are Available On-Line at **www.hittite.com** 



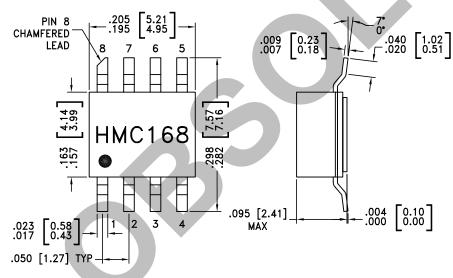
## GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 8 GHz

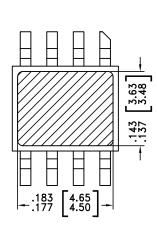
### **Absolute Maximum Ratings**

RF / IF Input	+13 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C



## **Outline Drawing**





#### NOTES

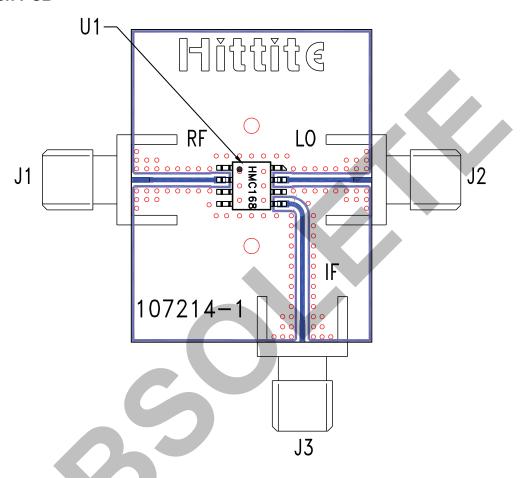
- 1. PACKAGE BODY MATERIAL: WHITE ALUMINA 92%
- 2. LEAD, PACKAGE BOTTOM MATERIAL: COPPER
- 3. PLATING: ELECTROLYTIC GOLD 100-200 MICROINCHES, OVER ELECTROLYTIC NICKEL 100-250 MICROINCHES.
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. PACKAGE LENGTH AND WIDTH DIMENSIONS DO NOT INCLUDE LID SEAL PROTRUSION .005 PER SIDE.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.





## GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 8 GHz

#### **Evaluation PCB**



### List of Materials for Evaluation PCB 102102 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC168C8 Mixer
PCB [2]	107214 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.